



Material Content Data Sheet



Sales Product Name		BSC0901NSI		Issued		1. August 2018		
MA#		MA001269492						
Package		PG-TDSON-8-6		Weight*		118.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.671	0.57	0.57	5664	5664
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		319	
wire	non noble metal	copper	7440-50-8	37.762	31.87	31.91	318711	319126
	noble metal	gold	7440-57-5	0.045	0.04	0.04	380	380
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		738	
	plastics	epoxy resin	-	6.209	5.24		52407	
leadfinish	inorganic material	silicondioxide	60676-86-0	37.431	31.59	36.90	315920	369065
	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12252	12252
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1397	1397
solder	non noble metal	tin	7440-31-5	0.019	0.02		161	
	noble metal	silver	7440-22-4	0.024	0.02		202	
heatspreader	non noble metal	lead	7439-92-1	0.912	0.77	0.81	7698	8061
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
heat sink CLIP	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.55	9.56	95542	95667
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		188	
*deviation	non noble metal	copper	7440-50-8	22.292	18.81	18.84	188143	188388
						Sum in total:	100.00	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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